# **BS170**

# **DMOS Transistors (N-Channel)**

# $\begin{array}{c} \textbf{TO-92} \\ \hline 131 (4.6) \\ \hline 097 \\ \hline 181 (4.6) \\ \hline 097 \\ \hline 181 (4.6) \\ \hline 097 \\ \hline 097 \\ \hline 097 \\ \hline 097 \\ \hline 098 (2.5) \\ \hline 0 \\ \hline 0$

Dimensions in inches and (millimeters)

# FEATURES

- High input impedance
  High-speed switching
- Angh-speed switching
  No minority carrier storage time
- Rominonty camer storage time
  CMOS logic compatible input
- No thermal runaway
- No inermal runaway
  No occordory brookd
- No secondary breakdown



## **MECHANICAL DATA**

**Case:** TO-92 Plastic Package **Weight:** approx. 0.18 g On special request, this transistor is also manufactured in the pin configuration TO-18.

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Value	Unit	
Drain-Source Voltage	V <sub>DSS</sub>	60	V	
Drain-Gate Voltage	V <sub>DGS</sub>	60	V	
Gate-Source Voltage (pulsed)	V <sub>GS</sub>	± 20	V	
Drain Current (continuous)	I <sub>D</sub>	300	mA	
Power Dissipation at $T_{amb} = 25 \text{ °C}$	P <sub>tot</sub>	0.831)	W	
Junction Temperature	Tj	150	°C	
Storage Temperature Range	T <sub>s</sub>	-65 to +150	°C	
<sup>1)</sup> Valid provided that leads are kept at ambient temp	perature at a distance of 2 mn	n from case.		

### Inverse Diode

	Symbol	Value	Unit
Max. Forward Current (continuous) at T <sub>amb</sub> = 25 °C	l <sub>F</sub>	0.5	A
Forward Voltage Drop (typ.) at $V_{GS} = 0$ , $I_F = 0.5$ A, $T_j = 25$ °C	V <sub>F</sub>	0.85	V



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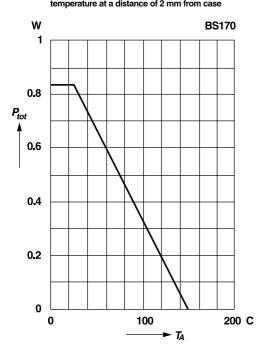
# ELECTRICAL CHARACTERISTICS

	Symbol	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage at $I_D = 100 \ \mu$ A, $V_{GS} = 0$	V <sub>(BR)</sub> DSS	60	80	-	V
Gate Threshold Voltage at $V_{GS} = V_{DS}$ , $I_D = 1 \text{ mA}$	V <sub>GS(th)</sub>	1.0	2	3.0	V
Gate-Body Leakage Current at $V_{GS}$ = 15 V, $V_{DS}$ = 0	I <sub>GSS</sub>	-	-	10	nA
Drain Cutoff Current at V_{DS} = 25 V, V_{GS} = 0	I <sub>DSS</sub>	-	-	0.5	μA
Drain-Source ON Resistance at $V_{GS}$ = 10 V, $I_D$ = 0.2 A	R <sub>DS(ON)</sub>	-	3.5	5.0	Ω
Thermal Resistance Junction to Ambient Air	R <sub>thJA</sub>	-	-	150 <sup>1)</sup>	K/W
Forward Transconductance at $V_{DS}$ = 10 V, $I_D$ = 0.2 A, f = 1 MHz	g <sub>m</sub>	-	200	-	mS
Input Capacitance at $V_{DS}$ = 10 V, $V_{GS}$ = 0, f = 1 MHz	C <sub>iss</sub>	-	30	-	pF
Switching Times at V <sub>GS</sub> = 10 V, $R_D$ = 100 $\Omega$					
Turn-On Time Turn-Off Time	t <sub>on</sub> t <sub>off</sub>		5 15	-	ns ns
<sup>1)</sup> Valid provided that leads are kept at ambient ter	mperature at a dis	tance of 2 m	nm from case.		

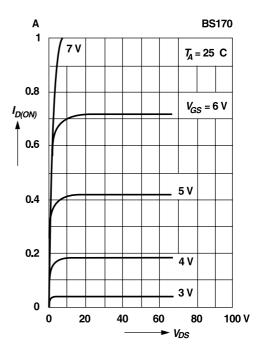


# **RATINGS AND CHARACTERISTIC CURVES BS170**

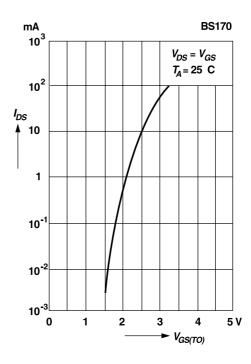
Admissible power dissipation versus temperature Valid provided that leads are kept at ambient temperature at a distance of 2 mm from case



Output characteristics Pulse test width 80 ms; pulse duty factor 1%

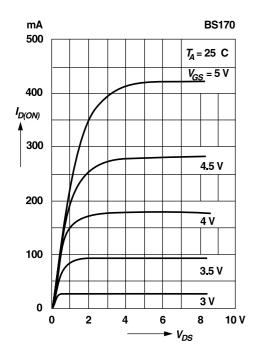


Drain-source current versus gate threshold voltage



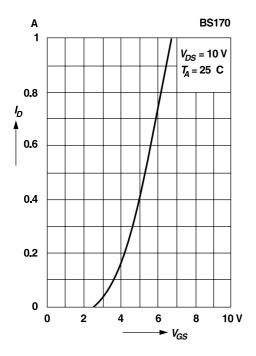
GENERAL SEMICONDUCTOR<sup>®</sup>

Saturation characteristics Pulse test width 80 ms; pulse duty factor 1%

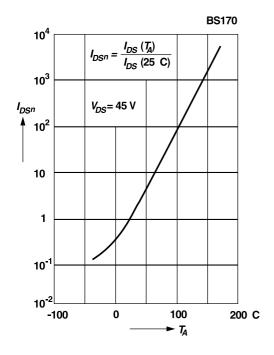


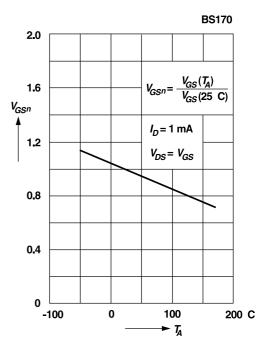
# **RATINGS AND CHARACTERISTIC CURVES BS170**

Drain current versus gate-source voltage Pulse test width 80 ms; pulse duty factor 1%



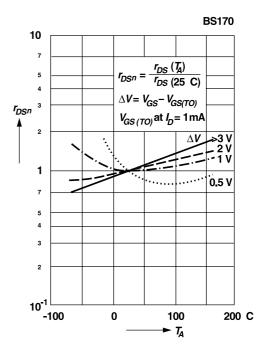
Normalized drain-source current versus temperature





Normalized gate-source voltage versus temperature

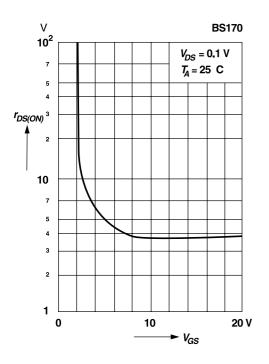
# Normalized drain-source resistance versus temperature



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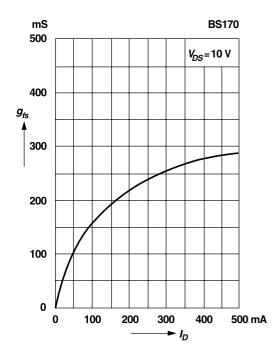
# **RATINGS AND CHARACTERISTIC CURVES BS170**

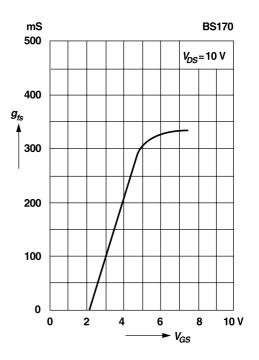
Drain-source resistance versus gate-source voltage



Transconductance versus drain current

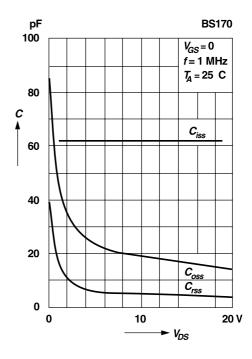
Pulse test width 80 ms; pulse duty factor 1%





Transconductance versus gate-source voltage Pulse test width 80 ms; pulse duty factor 1%

Capacitance versus drain-source voltage



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